

#### **Features**

- 3528 Top view PLCC SMD LED
- High reliability
- General purpose leads
- Peak wavelength λp=850nm
- Mechanically and spectrally matched to the phototransistor
- Low forward voltage
- High radiant intensity

# **Applications**

- Optoelectronic Switch
- IR Touch-Panel
- Industrial IR Equipment
- Consumer Electronics
- High Speed IR Communications

### **Description**

The IN-P32ZTIR is a popular 3528 top view package with versatile design capabilities. It is a PLCC type LED which can be used in various applications.

### **Recommended Solder Pattern**

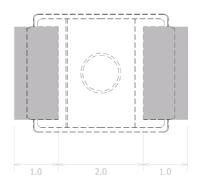
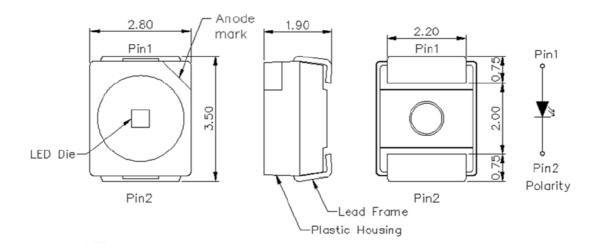


Figure 1. IN-P32ZTIR Solder Pattern

# Package Dimensions in mm



#### Notes.

- 1. All dimensions are in millimeters.
- 2. Tolerance is ± 0.10 mm unless otherwise noted

Figure 2. IN-P32ZTIR Package Dimensions



# Absolute Maximum Rating at 25°C (Note 1)

Product	Emission Color	P <sub>d</sub> (mW)	I <sub>F</sub> (mA)	I <sub>FP</sub> * (mA)	V <sub>R</sub> (V)	Top (°C)	T <sub>ST</sub> (°C)
IN-P32ZTIR	Infrared	165	100	1000	5	-40°C~+85°C	-40°C~+100°C

#### **Notes**

1. Ifp Conditions--Pulse Width  $\leq\!100\mu s$  and Duty  $\leq\!1\%.$ 

#### **ESD Precaution**

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol above denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are STATIC SENSITIVE devices. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

Please be advised that normal static precautions should be taken in the handling and assembly of this device to prevent damage or degradation which may be induced by electrostatic discharge (ESD).

### **Electrical Characteristics** $T_A = 25\%$ (Note 1)

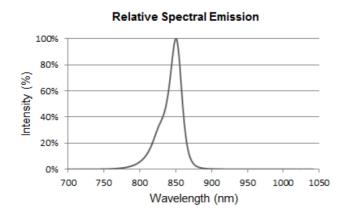
			V <sub>F</sub> (V)		λ(nm)			Viewing Angle	le (mW/sr)
Product	Emission Color	I <sub>F</sub> (mA)	min	max	λ <sub>D</sub>	λ <sub>P</sub>	Δλ	201/2	typ.
IN-P32ZTIR	Infrared	20	1.35	1.65	-	850	30	120	4.5

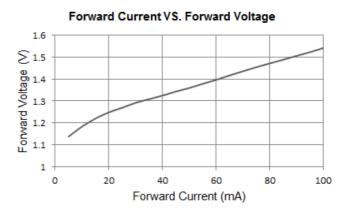
#### **Notes**

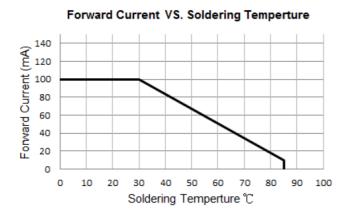
1. Performance guaranteed only under conditions listed in above tables.

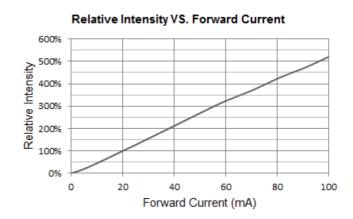


# **Typical Characteristic Curves**

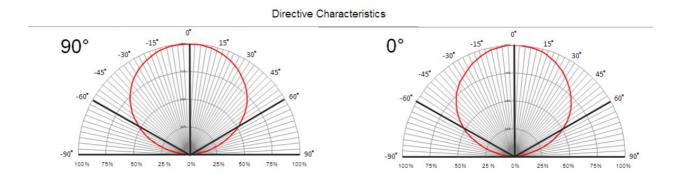








# **Typical Characteristic Curves – Radiation Pattern**

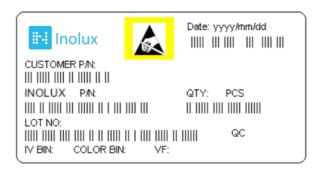




# **Ordering Information**

Product	Emission Color	Technology	Test Current I <sub>F</sub> (mA)	Radiant Intensity le (mW/sr) (Typ.)	Forward Voltage V <sub>F</sub> (V) (Typ.)	Orderable Part Number
IN-P32ZTIR	Infrared	AlGaAs	20	4.5	1.5	IN-P32ZTIR

# **Label Specifications**



### **Inolux P/N:**

I	N	-	Р	32	Z	T			IR	-	Х	Х	Х	Х
			Material	Package	Variation	Orientation	Current	Lens	Color				mizec p-off	
In	olux		P = PLCC Type		28 1.9mm PLCC 2	T = Top Mount	(Blank) = 20mA	(Blank) = clear	IR = 850nm					

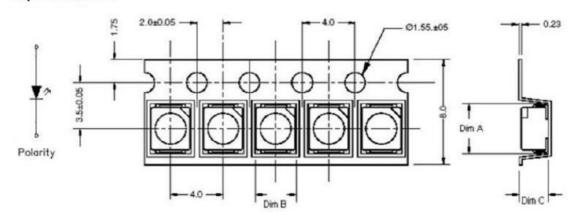
# Lot No.:

Z	2	0 1 7		01	24	001
Internal		Voor (2017	2010 \	Month	Data	Corial
Tracker		Year (2017	, 2018,)	MONTH	Date	Serial



# Packaging Information: 2000pcs Per Reel

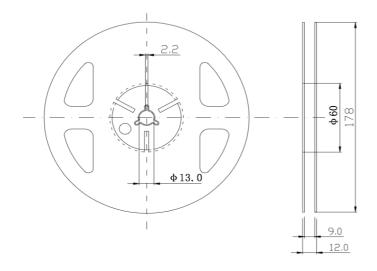
# Packaging Tape Dimension

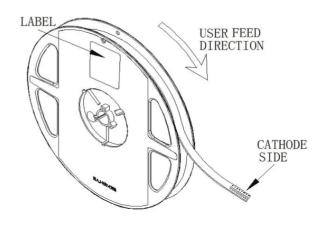


Dim. A	Dim. B	Dim. C	Q'ty/Reel
3.73±0.10	2.95±0.10	2.12±0.10	2K

Unit: mm

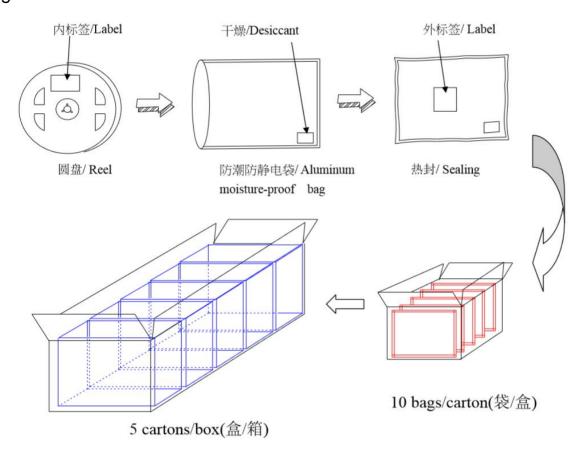
### **Reel Dimension**







# **Packing Dimension**



5 boxes per carton are available depending on shipment quantity.

	Specification	Material	Quantity
Carrier tape	Per EIA 481-1A specs	Conductive black tape	2000pcs per reel
Reel	Per EIA 481-1A specs	Conductive black	
Label	IN standard	Paper	
Packing bag	220x240mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	IN standard	Paper	Non-specified

#### Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv,  $\lambda_P$  and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

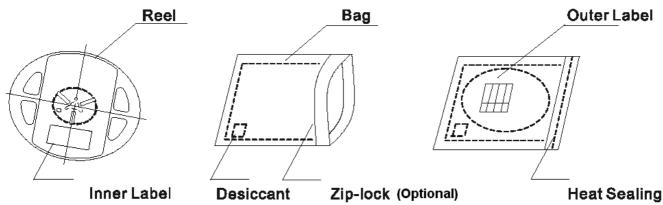


### **Dry Pack**

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

Upon request, a humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

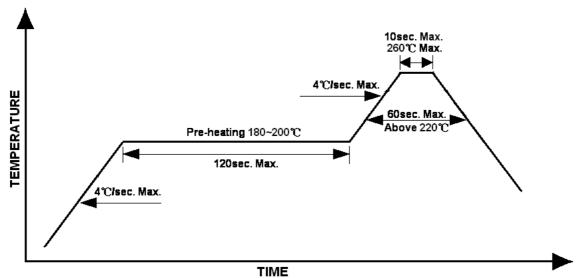
The packaging sequence is as follows:



# **Reflow Soldering**

- Recommended tin glue specifications: melting temperature in the range of 178~192 °C
- The recommended reflow soldering profile is as follows (temperatures indicated are as measured on the surface of the LED resin):

#### Lead-free Solder Profile





#### **Precautions**

- Avoid exposure to moisture at all times during transportation or storage.
- Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage.
- Avoid operation beyond the limits as specified by the absolute maximum ratings.
- Avoid direct contact with the surface through which the LED emits light.
- If possible, assemble the unit in a clean room or dust-free environment.

### Reworking

- Rework should be completed within 5 seconds under 260 °C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

### Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min</li>
- Ultra sonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100 °C max, <3min

#### **Cautions of Pick and Place**

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electro-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.





Reliability

Eliability	1	1			
Item	Frequency/ lots/ samples/ failures	Standards Reference	Conditions		
Precondition	For all reliability monitoring tests according to JEDEC Level 2	J-STD-020	1.) Baking at 85°C for 24hrs 2.) Moisture storage at 85°C/60% R.H. for 168hrs		
Solderability	1Q/ 1/ 22/ 0	JESD22-B102-B And CNS-5068	Accelerated aging 155°C/ 24hrs Tinning speed: 2.5+0.5cm/s Tinning: A: 215°C/ 3+1s or B: 260°C/ 10+1s		
Resistance to soldering heat		CNS-5067	Dipping soldering terminal only Soldering bath temperature A: 260+/-5°C; 10+/-1s B: 350+/-10°C; 3+/-0.5s		
Operating life test	1Q/ 1/ 40/ 0	CNS-11829	1.) Precondition: 85°C baking for 24hrs 85°C/ 60%R.H. for 168hrs 2.) Tamb25°C; IF=20mA; duration 1000hrs		
High humidity, high temperature bias	1Q/ 1/ 45/ 0	JESD-A101-B	Tamb: 85°C Humidity: 85% R.H., IF=5mA Duration: 1000hrs		
High temperature bias	1Q/ 1/ 20	IN specs.	Tamb: 55°C IF=20mA Duration: 1000hrs		
Pulse life test	1Q/ 1/ 40/ 0		Tamb25°C, If=20mA,, Ip=100mA, Duty cycle=0.125 (tp=125 μ s,T=1sec) Duration 500hrs)		
Temperature cycle	1Q/ 1/ 76/ 0	JESD-A104-A IEC 68-2-14, Nb	A cycle: -40 degree C 15min; +85 degree C 15min Thermal steady within 5 min 300 cycles 2 chamber/ Air-to-air type		
High humidity storage test	1Q/ 1/ 40/ 0	CNS-6117	60+3°C 90+5/-10% R.H. for 500hrs		
High temperature storage test	1Q/ 1/ 40/ 0	CNS-554	100+10°C for 500hrs		
Low temperature storage test	1Q/ 1/ 40/ 0	CNS-6118	-40+5°C for 500hrs		



# **Revision History**

Changes since last revision	Page	Version No.	Revision Date
Initial Release		1.0	01-29-2019

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